

PRIOR ART

PATENT ABSTRACTS OF JAPAN

Ref1

(11)Publication number : 2003-243342

(43)Date of publication of application : 29.08.2003

(51)Int.Cl.

H01L 21/304

B24B 37/00

G08J 5/14

G08K 3/00

G08L101/00

(21)Application number : 2002-038463

(71)Applicant : UNITIKA LTD

(22)Date of filing : 15.02.2002

(72)Inventor : TANABE KATSUYUKI

(54) POLISHING PAD

(57)Abstract:

PROBLEM TO BE SOLVED: To provide a polishing pad which is capable of precisely polishing a semiconductor wafer and the like without contaminating or damaging the surface of the polished work.

SOLUTION: The polishing pad is mainly formed of composite materials composed of a resin matrix and inorganic materials displaying polishing properties. The composite materials are formed through an organic-inorganic hybrid synthesis method, and the inorganic materials are substantially, uniformly dispersed in the resin matrix. The inorganic materials are 10 nm or below in a grain diameter.